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35th IEEE VLSI TEST SYMPOSIUM

Caesars Palace, Las Vegas, NV, USA

April 9 - 12, 2017

Call for Papers

The **IEEE VLSI Test Symposium** (VTS) explores emerging trends and novel concepts in testing, debug and repair of microelectronic circuits and systems. Major topics include, but are not limited to:

- *Analog/Mixed-Signal/RF Test*
- *ATPG & Compression*
- *ATE Architecture & Software*
- *Automotive Test & Safety*
- *Built-In Self-Test (BIST)*
- *Defect & Current Based Test*
- *Defect/Fault Tolerance*
- *Delay & Performance Test*
- *Design for Testability (DFT)*
- *Design Verification/Validation*
- *Embedded System & Board Test*
- *Embedded Test Methods*
- *Emerging Technologies Test*
- *FPGA Test*
- *Fault Modeling and Simulation*
- *Hardware Security*
- *Low-Power IC Test*
- *Microsystems/MEMS/Sensors Test*
- *Memory Test and Repair*
- *On-Line Test & Error Correction*
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- *System-on-Chip (SOC) Test*
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- *Test of Biomedical Devices*
- *Test of High-Speed I/O*
- *Test Quality and Reliability*
- *Test Resource Partitioning*
- *Transients and Soft Errors*
- *2.5D, 3D and SiP Test*

The VTS Program Committee invites **original, unpublished Paper Submissions** for VTS 2017**.** Paper submissions should be complete manuscripts, up to six pages (inclusive of figures, tables, and bibliography) in a standard IEEE two-column format; papers exceeding the page limit will be returned without review. Authors should clearly explain the significance of the work, highlight novel features, and describe its current status. On the title page, please include: author name(s) and affiliation(s), and the mailing address, phone number, and e-mail address of the contact author. A 50-word abstract and five keywords identifying the topic area are also required.

Proposals for the **Innovative Practices** and **Special Sessions** tracks are also invited. The innovative practices track highlights cutting-edge challenges faced by test practitioners, and innovative solutions employed to address them. Special sessions can include invited presentations on hot topics, panels, embedded tutorials. Innovative practices and special session track proposals should include a title, name and contact information of the session organizer(s), a 150-to-200 word abstract, and a list of prospective participants.

All submissions are to be made electronically through the VTS website. The deadline for all submissions is **October 14th, 2016**. Detailed instructions for submissions will be found at the symposium website ***http://www.tttc-vts.org***. Authors will be notified of the disposition of their papers by **December 20th, 2016**. A submission will be considered as evidence that, upon acceptance, the author(s) will submit a final camera-ready version of the paper by **February 10th, 2017**. Registration of at least one author by the camera-ready deadline and presentation of the paper at the symposium are also required for inclusion of the paper in the published proceedings. In the case of innovative practices and special sessions, the organizers commit to submitting a session title, abstract and list of participants for inclusion in the symposium proceedings.

VTS 2017 will present a **Best Paper Award**, a **Best Special Session Award,** and a **Best Innovative Practices Session Award** based on the evaluations of reviewers, attendees, and an invited panel of judges. We also plan to organize various **Student Activities** including the **TTTC Best Doctoral Thesis Contest**, details for which will be made available through the VTS website. The Best Paper of VTS 2017 and the Best Innovative Practices presentation will be invited to resubmit to the IEEE Design & Test of Computers where they will undergo a regular, but expedited, review process.

TTTC Test Technology Educational Program (TTEP) tutorials on emerging test technology topics will be offered in conjunction with VTS 2017. Tutorial proposals should be submitted according to TTEP 2017 submission guidelines, which will be posted on ***http://computer.org/tab/tttc/teg/ttep***.

VTS 2017 is sponsored by the Test Technology Technical Council (TTTC) of the IEEE Computer Society and the IEEE Philadelphia Section. For more information on the symposium, please visit the VTS website at ***http://www.tttc-vts.org*** or contact:

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